

UNIVERSAL CLAMPING MECHANISM

ABSTRACT

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A method is provided for processing a lead frame. Generally, a first surface of a lead frame base tape is placed on a first surface of the lead frame. A second surface of the lead frame base tape is placed on a first surface of a porous block. A vacuum is placed on a second surface of the porous block. A device for processing lead frames
10 comprises a porous block with a first side and a second side, and a vacuum system connected to the first side of the porous block. The device may also include devices for attaching chips to the lead frame and wire bonding the chips to the lead frame.